

Attorney Docket No.: M-11590 US

DECLARATION FOR PATENT APPLICATION AND POWER OF ATTORNEY

		ntor, I hereby declare th					
My residence, post office address and oitizenship are as stated below adjacent to my name.							
first and joint in	(VEIXEO) Ontdos	nal, first and sole invention of matter, or an loof the opplication cntit	e listed helow) o Improvement there	r sumeti mant			
SEMICONDUCTOR DEVICE HAVING MULTI-CHIP PACKAGE STRUCTURE							
which (check)	and is amended by the Preliminary Amendment attached hereto. was filed on as Application Scrial No. and was amended on (if applicable).						
I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.							
I acknowledge the duty to disclose information, which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.							
Thereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed:							
		Prior Foreign Applic	ation(s)		Priority	Claimed	
Number		Country	Day/Month	Year Filed	Yes	No	
N/A							
I hereby claim the benefit under Title 35, United States Code, § 119(c) of any United States provisional application(s) listed below:							
Provisional Application Number				Filing Date			
		/A			·	. ,,,,	
I hereby claim the bonefit under Title 35, United States Code, § 120 of any United States application(s) or PCT international application(s) designating the United States of America listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior application(s) in the manner provided by the first paragraph of Title 35, United States Code, so the following the disclosure information which is metallical an ententability as defined in							
Application S	igriai ::	S. Piling	Date 5	atus (paiemes),	penairig, <u></u>	Jelaulier)	

I hereby appoint the following practitioners to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith:

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I declare that all statements made herein of my own knowledge are true, all statements made herein on information and belief are believed to be true, and all statements made herein are made with the knowledge that whoever, in any matter within the jurisdiction of the Patent and Trademark Office, knowingly and willfully falsifies, conceals, or covers up by any trick, scheme, or device a material fact, or makes any false, fictitious or fraudulent statements or representations, or makes or uses any false writing or document knowing the same to contain any false, fictitious or fraudulent statement or entry, shall be subject to the penalties including fine or imprisonment or both as set forth under 18 U.S.C. 1001, and that violations of this paragraph may jeopardize the validity of the application or this document, or the validity or enforceability of any patent, trademark registration, or certificate resulting therefrom

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